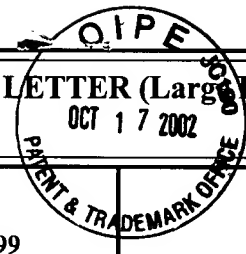


28158



AMENDMENT TRANSMITTAL LETTER (Large Entity) Applicant(s): Masanori MINAMIO, et al.		Docket No. JEL 30763 PCT
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Serial No. 09/380,312	Filing Date August 31, 1999	Examiner L. C. Cruz	Group Art Unit 2815
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Invention:
RESIN MOLDED TYPE SEMICONDUCTOR DEVICE AND A METHOD OF MANUFACTURING THE SAME

TO THE ASSISTANT COMMISSIONER FOR PATENTS:
Transmitted herewith is an amendment in the above-identified application.
The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED						
	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE	
TOTAL CLAIMS	30 -	20 =	10 x	\$18.00	\$180.00	
INDEP. CLAIMS	9 -	9 =	0 x	\$84.00	\$0.00	
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00	
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$180.00	

- ☐ No additional fee is required for amendment.
- ☐ Please charge Deposit Account No. _____ in the amount of _____
A duplicate copy of this sheet is enclosed.
- ☒ A check in the amount of \$180.00 to cover the filing fee is enclosed.
- ☒ The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 19-4375
A duplicate copy of this sheet is enclosed.
 - ☒ Any additional filing fees required under 37 C.F.R. 1.16.
 - ☒ Any patent application processing fees under 37 CFR 1.17.

Signature

Dated: October 17, 2002

James E. Ledbetter, Esq.
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Washington, DC 20036
Tel.: (202) 785-0100
Fax: (202) 408-5200

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I certify that this document and fee is being deposited on _____ with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.
Signature of Person Mailing Correspondence
Typed or Printed Name of Person Mailing Correspondence

CC:



#19/C

1-17-03

L. Spruell

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

fee OK

Inventors: Masanori Minamio, et al.

Art Unit: 2815

Appln. No.: 09/380,312 /

Examiner: L.C. Cruz

Filed: August 31, 1999 /

For: RESIN MOLDED TYPE SEMICONDUCTOR DEVICE AND A
METHOD OF MANUFACTURING THE SAMEAMENDMENTAssistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action mailed July 17, 2002, the Applicants hereby request amendment of the above-identified application as follows:

IN THE DRAWINGS

Proposed revisions of Figs. 1, 3, 5 and 6 are submitted herewith for approval, with a Letter to the Official Draftsman.

IN THE CLAIMS

Please amend the claims to read as follows (Exhibit I contains a marked up version):

1. (Amended) A resin molded type semiconductor device comprising: a semiconductor chip which is mounted on a die pad of a lead frame; thin metal wires which electrically connect terminals of an upper face of said semiconductor chip to inner lead portions

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